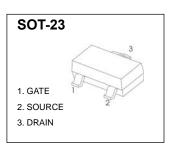


# JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO., LTD

# **SOT-23 Plastic-Encapsulate MOSFETS**

# CJ3415 P-Channel 20-V(D-S) MOSFET

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> MAX	I <sub>D</sub>
	50mΩ@-4.5V	
-20 V	60mΩ@-2.5V	-4A
	100mΩ@-1.8V	



#### **FEATURE**

• Excellent R<sub>DS(ON)</sub>, low gate charge,low gate voltages

#### **APPLICATION**

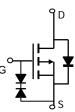
• Load switch and in PWM applicatopns

#### **MARKING**



R15=Device code Solid dot = Green molding compound device,if none, the normal device

# **Equivalent Circuit**



### Maximum ratings (T<sub>a</sub>=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	-20	V
Gate-Source Voltage	V <sub>GS</sub>	±8	V
Continuous Drain Current (t≤10s)	I <sub>D</sub>	-4.0	Α
Maximum Power Dissipation (note4)	P <sub>D</sub>	1.3	W
Thermal Resistance from Junction to Ambient(note4)	$R_{\theta JA}$	96.2	°C/W
Operation Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 ~+150	°C

## **MOSFET ELECTRICAL CHARACTERISTICS**

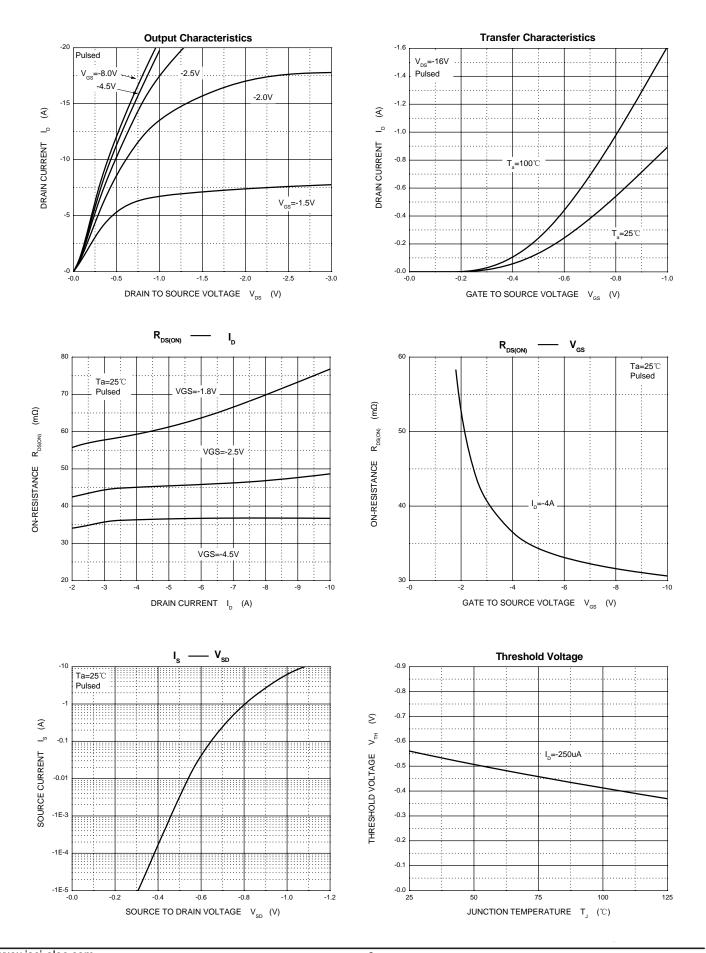
## T<sub>a</sub>=25 ℃ unless otherwise specified

Parameter	Symbol	Test Condition	Min	Тур	Max	Units
Static Parameters				•		
Drain-source breakdown voltage	V(BR) DSS	Vgs = 0V, ID =-250µA	-20			V
Gate threshold voltage	VGS(th)	$V_{DS} = V_{GS}$ , $I_{D} = -250 \mu A$	0V, ID =-250μA -20   VGS, ID =-250μA -0.3 -0.56   0V, VGS =±8V 0V, VGS =±4.5V 0.037   16V, VGS =0V 0.045 0.045   4.5V, ID =-4A 0.080 0.080   1.8V, ID =-2A 0.080 0.080   5V, ID =-4A 8 0.080   1.0V, VGS =0V 1450 0.00   1.10V, VGS =0V, f = 1MHz 0.5 0.00   1.10V, VGS =0V, f = 1MHz 17.2 0.00   1.10V, VGS =-4.5V, ID =-4A 1.3 0.00   1.10V, VGS =-4.5V, ID =-4A 1.3 0.00   1.10V, VGS =-4.5V 17 0.00   1.10V, VGS =-4.5V 10 0.00   1.10V, VGS =-4.5V 0.00 0.00   1.10V, VGS =-4.5V 0.00 0.00   1.10V, VGS =-4.		-1	V
Cata hadii laskana airmaat		V <sub>DS</sub> =0V, V <sub>GS</sub> =±8V			±10	
Gate-body leakage current	$I_{GSS}$	V <sub>DS</sub> =0V, V <sub>GS</sub> =±4.5V			±1	μΑ
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V			-1	
		Vgs =-4.5V, ID =-4A		0.037	0.050	
Drain-source on-state resistance(note1)	RDS(on)	Vgs =-2.5V, ID =-4A		0.045	0.060	Ω
		Vgs =-1.8V, ID =-2A		0.080	0.100	
Forward transconductance(note2)	<b>g</b> FS	VDS =-5V, ID =-4A	8			S
Body diode voltage(note2)	V <sub>SD</sub>	I <sub>S</sub> =-1A,V <sub>GS</sub> =0V			-1	V
Dynamic Parameters (note3)						
Input capacitance	C <sub>iss</sub>			1450		
Output capacitance	Coss	Vps =-10V,Vgs =0V,f =1MHz		205		pF
Reverse transfer capacitance	C <sub>rss</sub>			160		
Gate resistance	Rg	V <sub>DS</sub> =0V,V <sub>GS</sub> =0V,f =1MHz		6.5		Ω
Switching Parameters						
Total gate charge	Qg			17.2		
Gate-Source charge	$Q_{gs}$	VDS =-10V,VGS =-4.5V,ID =-4A		1.3		nC
Gate-drain charge	$Q_{gd}$			4.5		
Turn-on delay time (note3)	td(on)			9.5		
Turn-on rise time(note3)	tr	V <sub>DS</sub> =-10V, V <sub>GS</sub> =-4.5V		17		
Turn-off delay time(note3)	td(off)	RGEN =3 $\Omega$ , R <sub>L</sub> =2.5 $\Omega$ ,		94		ns
Turn-off fall time(note3)	t <sub>f</sub>			35		

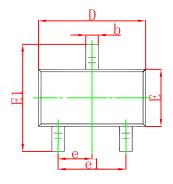
#### Notes:

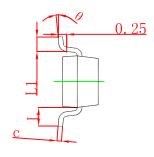
- 1. Repetitive rating, pulse width limited by junction temperature.
- 2. Pulse Test : Pulse width  $\leq$  300 $\mu$ s, duty cycle  $\leq$  2%.
- 3. These parameters have no way to verify.
- 4. Device mounted on 1"×1" FR-4 PCB with high coverage 2oz Copper ,double sided. Copper, t≤10s.

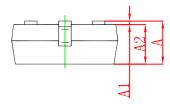
# **Typical Characteristics**



# **SOT-23 Package Outline Dimensions**

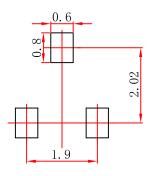






Cumbal	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950	TYP	0.03	7 TYP	
e1	1.800	2.000	0.071	0.079	
L	0.550	REF	0.022	2 REF	
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

# **SOT-23 Suggested Pad Layout**



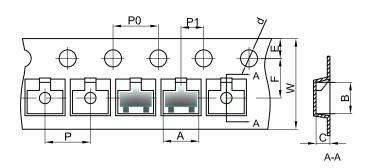
#### Note:

- 1. Controlling dimension: in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

#### **NOTICE**

JSCJ reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. JSCJ does not assume any liability arising out of the application or use of any product described herein.

### SOT-23 Embossed Carrier Tape

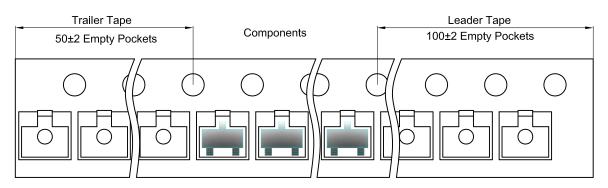


#### Packaging Description:

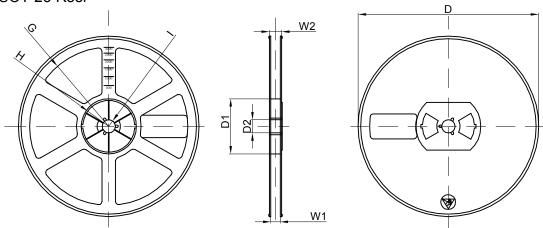
SOT-23 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 3,000 units per 7" or 17.8cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).

	Dimensions are in millimeter									
Pkg type A B C d E F P0 P P1 W								W		
SOT-23	3.15	2.77	1.22	Ø1.50	1.75	3.50	4.00	4.00	2.00	8.00

### SOT-23 Tape Leader and Trailer



#### SOT-23 Reel



Dimensions are in millimeter									
Reel Option	Reel Option   D   D1   D2   G   H   I   W1   W2								
7"Dia	Ø178.00	54.40	13.00	R78.00	R25.60	R6.50	9.50	12.30	

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
3000 pcs	7 inch	30,000 pcs	203×203×195	120,000 pcs	438×438×220	